

[DOCUMENT NAME] PATENT APPLICATION

[CASE NUMBER] 51255901

[APPLICATION DATE] August 31, 1998

[SUBMITTED TO] Patent Office Director

[IPC] Q01R 1/06

H01L 21/60

[TITLE OF THE INVENTION] WAFER TEST PROBE, MANUFACTURING METHOD THEREFOR AND SEMICONDUCTOR DEVICE TESTED BY THE PROBE

[NUMBER OF CLAIMS] 5

[INVENTOR]

[ADDRESS] Mitsubishi Denki Kabushiki Kaisha
2-2-3 Marunouchi, Chiyoda-ku, Tokyo

[FULL NAME] Shigeki MAEKAWA

[INVENTOR]

[ADDRESS] Mitsubishi Denki Kabushiki Kaisha
2-2-3 Marunouchi, Chiyoda-ku, Tokyo

[FULL NAME] Megumi TAKEMOTO

[INVENTOR]

[ADDRESS] Mitsubishi Denki Kabushiki Kaisha
2-2-3 Marunouchi, Chiyoda-ku, Tokyo

[FULL NAME] Yoshihiro KASHIBA

[INVENTOR]

[ADDRESS] Mitsubishi Denki Kabushiki Kaisha
2-2-3 Marunouchi, Chiyoda-ku, Tokyo

[FULL NAME] Yoshinori DEGUCHI

[INVENTOR]

[ADDRESS] Mitsubishi Denki Kabushiki Kaisha
2-2-3 Marunouchi, Chiyoda-ku, Tokyo

[FULL NAME] Kazunobu MIKI

[APPLICANT]

[ID NUMBER] 000006013

[NAME] Mitsubishi Denki Kabushiki Kaisha

[AGENT]

[ID NUMBER] 100102439

[PATENT AGENT]

[NAME] Kaneo MIYATA

[AGENT]

[ID NUMBER] 100103894

[PATENT AGENT]

[NAME] Takeshi IEIRI

[AGENT]

[ID NUMBER] 100092462

[PATENT AGENT]

[NAME] Yahei TAKASE

[INDICATION OF FEES]

[ACCOUNT] 011394

[PAYMENT] 21000

[LIST OF FILED ITEM]

[ITEM NAME] SPECIFICATION 1

[ITEM NAME] DRAWINGS 1

[ITEM NAME] ABSTRACT 1

[GENERAL POWER OF ATTORNEY NO.]

9704079

[DOCUMENT NAME] SPECIFICATION

[TITLE OF THE INVENTION] SEMICONDUCTOR DEVICE TEST PROBE,
MANUFACTURING METHOD THEREFOR AND SEMICONDUCTOR DEVICE
TESTED BY THE PROBE

[CLAIMS]

[Claim 1] In a semiconductor device test probe for testing a function of an integrated semiconductor device by urging a tip portion against an electrode pad of the integrated semiconductor device to establish an electrical contact between the tip portion and the electrode pad; a semiconductor device test probe characterized in that said probe includes a side surface portion and the tip portion, said tip portion is a spherical curved surface, and that the radius of curvature r of said curved surface, with respect to the electrode pad thickness t , is made $9t \leq r \leq 35t$.

[Claim 2] In a semiconductor device test probe for testing a function of an integrated semiconductor device by urging a tip portion against an electrode pad of the integrated semiconductor device to establish an electrical contact between the tip portion and the electrode pad; a semiconductor device test probe characterized in that said probe includes a side surface portion and the tip portion, said tip portion is a spherical curved surface, said curved surface has a first curved surface which is substantially positioned in the direction of slippage of the probe when the probe is urged against the electrode pad and slipped relative to the electrode pad and which is larger than a second curved surface opposite to said first curved surface, and that the radius of curvature of said first curved surface is made of from $7 \mu\text{m}$ to $30 \mu\text{m}$.

[Claim 3] A method for manufacturing the semiconductor device test probe as claimed in claim 2, comprising the steps of: roughing said tip portion of said curved surface by abrading by means of electrolyte abrasion or abrading particles to form a symmetrical spherical curved surface; and finishing said tip portion by sliding it on an abrasive member comprising an elastically deformable thick film fixed to a substrate and having abrasive particles therein

or thereon directly or through a metallic film.

[Claim 4] The semiconductor device test probe as claimed in claim 1 or 2, wherein said probe is made of a sintered metallic material made from a powdery material, and said probe is heat treated, the heat treatment conditions being a non-oxidizing atmosphere, at the treatment temperature of equal to or less than the recrystallization temperature of said metallic material and said non-oxidizing gas is pressurized.

[Claim 5] A semiconductor device tested by the semiconductor device test probe as claimed in any one of claims 1, 2 and 4, wherein the test is achieved by urging said probe against the electrode pad of the semiconductor device, providing a relative sliding movement between said probe and said electrode pad to expel the electrode pad material by making a lamination stack.

[DETAILED DESCRIPTION OF THE INVENTION]

[0001]

[Technical Field of the Invention]

This invention relates to a semiconductor device test probe, manufacturing method therefor and a semiconductor device tested by such the probe for testing the electrical property confirmation test (wafer test) of a semiconductor integrated circuit, display test for the display devices or operation test of an electronic substrate.

[0002]

[Prior Art]

With the conventional test probe as shown in Fig. 9(a), the testing (probing) is carried out by attaching a probe 202 having a for and bent into a hook-like shape to a probe card 201 which is vertically movable, and pushing the probe 202 against a test pad of a semiconductor integrated circuit (referred to as an electrode pad herein after) in such a manner that an oxide film on the pad surface is broken off to establish true contact (electrical contact) between the probe and a fresh surface of the pad. The condition of a probe tip under the probing is shown in Fig. 9(b). For the sake of easy understanding, Fig. 9(b) is illustrated in the form of a simplified model with respect to dimensions and the like. As shown in Fig. 9(b), the tip 200 of the conventional probe is originally finished to have a flat end face, so that at the time of probing the whole of the flat tip portion is brought into contact and an oxide film 204 and

contaminants on the surface of the electrode pad 203 are left interposed between the probe tip and the pad surface.

[0003]

Further pressing of the probe against the electrode pad to drive it by 50 - 100 μ m further downward (overdrive) causes the inclined tip of the probe to slip and break a portion of the oxide film 204 to make the conducting portion 206 through which an electrical true contact is established, permitting the conduction test to be achieved. At this time, the probe is slightly rotated by flexure. Therefore, in a probe card having a number of probes with a flat finished tip, an angle of the flat surface at the probe tip portion is not equal to each other during the overdriving, thus posing a problem that the contact state is not stable.

[0004]

Also, in Japanese Patent Laid-Open No. 6-61316, an example is disclosed in which the tip of the probe is formed into a sphere-shape or an oval sphere-shape in order not to damage the electrode pad of the integrated semiconductor device. In this example, differing from the one in which the tip portion is finished flat, any problem due to the deviation of the contacting surface areas does not arise.

[0005]

Japanese Patent Laid-Open No. 8-166407 discloses an example of a probe for testing lead portions (final test) of a semiconductor device, wherein the radius of curvature r of the tip portion of the probe is made from $0.5R$ to $5R$ (R is the diameter of the tip portion of the probe), whereby the contacting area becomes more stable as compared to the case where the tip portion is flat for the reasons the same as that for the foregoing spherical tip portion, thereby to suppressing the temperature rise of the probe and preventing the welding of Sn. Here, the minimum radius of curvature is set at the machining limitation or to be a semi-sphere shape. Also, the reasons for the maximum limit of $5R$ is explained to be for the purpose of preventing the ridge defined between the side surface portion and the spherical tip portion from planing the plated Sn.

[0006]

Japanese Patent Laid-Open No. 5-273237 discloses a structure for bringing the tip of the probe into a line contact with an electrode pad.

According to this paper, even if the electrode pad is small, the probe does not fall off from the pad, allowing an accurate measurement, so that the tip portion may preferably have the shape as shown in Fig. 10.

[0007]

Further, Japanese Patent Laid-Open No. 8-152436 discloses an example as shown in Fig. 11 in which the probe comprises a first surface 207 that becomes parallel to the pad surface when the tip of the probe is brought into contact with the electrode pad of the semiconductor device and a second surface 208 that is parallel to the pad surface during the test. According to this probe, the first surface 207 causes an oxide film on the electrode pad to separate to expose the surface without the oxide film, thereby to ensure the good contact state. The second surface is three times larger than the first surface, ensuring the sufficient contact surface area.

[0008]

Also, since tungsten used as the probe material is made of sintered powder material, the finishing of the tip shape is often achieved by the electrolytic abrasion, but since agglutination can easily take place when the surface coarseness is large, the forgoing Japanese Patent Laid-Open No. 8-166407 proposes a measure for decreasing the surface coarseness by selecting a suitable electrolytic conditions. Also, the effectiveness of polishing the tip into a mirror surface is disclosed also in Japanese Patent Laid-Open No. 6-294844.

[0009]

[The Problem to be Solved by the Invention]

Since the conventional probe is constructed as above and as shown in Fig. 9, the true contact area between the tip portion of the probe and the electrode pad at the time of test (electrically conductive portion 206) is extremely small, a sufficient conduction was some times not properly provided. Also, the repeated probing causes the oxide films 204 to build up on the tip portion 200 of the probe, the true contact surface area relative to the electrode pad is decreased, making the electrical conduction unstable.

[0010]

Also, even though the stress may be decreased by making the tip portion spherical, the oxide film cannot sufficiently be removed, so that a

sufficient true contact surface area cannot be maintained. That is, even when the contact surface is made large, the remains of the aluminum oxide film immediately below the spherical surface impedes the stable contacting and it is necessary to rather frequently remove the aluminum oxide that attaches to the tip portion as the number of times of contacts increase.

[0011]

In the structure for achieving the separation of the oxide film and the establishment of a true electrical contact by different respective tip surfaces such as shown in Fig. 11 which is an arrangement suggested to solve the problem of residual oxide film, it was found that, while good results were obtained at the initial state, some probes generate poor contacts as the number of times of contacts increases. As a result of the observation and the analysis of the state of the probes in connection with this problem, it was found that when the second contact surface is brought into contact with the electrode pad and repeat this test several times, the second contact surface has aluminum attached thereto, which increases the contact resistance when oxidized. The above assumption is considered reasonable from the fact that this phenomenon generated more often after the exchange of the semiconductor wafer and the halt of the line, i.e., when the test is interrupted for more than several minutes. It is considered that the reason some probes generated poor contacts and some other did not is because the contact surfaces have different from angles in view of the fact that the number of probes are simultaneously brought into contact with the electrode pads, so that it is difficult in the arrangement shown in Fig. 11 to work the first and the second flat surfaces to precision and posed problem in multi-pin measurement which will be more often required in the future.

[0012]

In order to prevent an aluminum attachment, although the probe surface was polished into a mirror surface, it was difficult to prevent an aluminum attachment completely. It was also found that, since the tungsten probe material has cavity holes therewithin because of it being a sintered body, aluminum enters into the cavities and oxidize, leading to a poor contact. On the other hand, the probe tip portion is getting more slippery because of the decreased surface roughness. In the case of the progress of the amount of over drive to obtain the stable contact, another problem was that the probe tip

can be slipped out of the electrode pad.

[0013]

Also, when the wire bonding is achieved to the semiconductor device after it is tested by the probes, the probe trace causes the yield of the bonding to be decreased. Particularly, when the electrode pad is made small and at the same time the bonding size is made small to make the semiconductor device small in order to increase the number of semiconductor device taken per one wafer, the size of the probe trace is desired to be small which disadvantageously affects the electrical contact, resulting in that the bonding yield was decreased.

[0014]

The present invention is made to solve the above problems and has as its object the provision of a test probe and a manufacturing method therefor in which the true contact surface area between a probe tip portion and an electrode pad can be increased and a sufficient reliable electrical connection with a minimum probe sliding amount can be established.

[0015]

The present invention is to provide a test probe and a manufacturing method therefor which is maintenance free in the sense that aluminum does not attach to the tip portion.

[0016]

Also, the present invention is to provide a reliable semiconductor device by making the probe traces small.

[0017]

[Measure for Solving the Problem]

According to the semiconductor device test probe of the first construction of the present invention, in a semiconductor wafer test probe for testing a function of an integrated semiconductor device by urging a tip portion against an electrode pad of the integrated semiconductor device to establish an electrical contact between the tip portion and the electrode pad; a semiconductor device test probe is characterized in that said probe includes a side surface portion and the tip portion, said tip portion is a spherical curved surface, and that the radius of curvature r of said curved surface, with respect to the electrode pad thickness t , is made $9t \leq r \leq 35t$.

[0018]

According to the semiconductor device test probe of the second construction of the present invention, in a semiconductor wafer test probe for testing a function of an integrated semiconductor device by urging a tip portion against an electrode pad of the integrated semiconductor device to establish an electrical contact between the tip portion and the electrode pad; a semiconductor device test probe is characterized in that said probe includes a side surface portion and the tip portion, said tip portion is a spherical curved surface, said curved surface has a first curved surface which is substantially positioned in the direction of slippage of the probe when the probe is urged against the electrode pad and slipped relative to the electrode pad and which is larger than a second curved surface opposite to said first curved surface, and that the radius of curvature of said first curved surface is made of from $7\text{ }\mu\text{m}$ to $30\text{ }\mu\text{m}$.

[0019]

According to the method for manufacturing the semiconductor device test probe of the first construction of the present invention, in the test probe as in the second construction, the method comprises the steps of: roughing said tip portion of said curved surface by abrasing by means of electrolyte abrasion or abrasing particles to form a symmetrical spherical curved surface; and finishing said tip portion by sliding it on an abrasive member comprising an elastically deformable thick film fixed to a substrate and having abrasive particles therein or thereon directly or through a metallic film.

[0020]

According to the semiconductor device test probe of the fourth construction of the present invention, in the probe according to the first or second construction, said probe is made of a sintered metallic material made from a powdery material, and said probe is heat treated, the heat treatment conditions being a non-oxidizing atmosphere, at the treatment temperature of equal to or less than the recrystallization temperature of said metallic material and said non-oxidizing gas is pressurized.

[0021]

According to the semiconductor device of the fifth construction of the present invention, the test is achieved by urging the semiconductor device test

probe as in one of the first, second and fourth constructions against the electrode pad of the semiconductor device, providing a relative sliding movement between said probe and said electrode pad to expel the electrode pad material by making a lamination stack.

[0022]

[Embodiments of the Invention]

Embodiment 1

The embodiments of the present invention will now be described in conjunction with figures. Figs. 1 and 2 are explanation views showing a state of an electrode pad and a test probe of the first embodiment of the present invention. In the figures, reference numeral 1 is the test probe and 2 is the electrode pad, which is a film of Al-Cu of a thickness of the order of $0.8\ \mu\text{m}$ for a typical logic integrated semiconductor device such as DRAM. The electrode pad may be $2\text{--}3\ \mu\text{m}$ for a special purpose semiconductor device such as a power device. The reference numeral 3 is the crystalline orientation of the electrode pad, 4, 5 and 6 are slip surfaces, 7 a tangent vector of the probe tip, 8 an oxide film on the electrode pad surface, 9 an oxide film attached to the probe, 10 an electrically conducting portion and 11 are sheared pieces.

[0023]

As illustrated in Fig. 2, the electrical conduction portion between the probe 1 and the electrode pad 2 can be obtained by sliding the probe 1 at the time of probing on the oxide film 8 and breaking the oxide film 8 on the electrode pad 2, thereby bringing the probe 1 into contact with the fresh surface of the electrode pad 2. The probe 1 is not vertical to the surface of the electrode pad 2, but is illustrated as being tilted by 8 degrees, which tilt angle generates a relative slippage between the probe 1 and the electrode pad 2. Also illustrated is a contour as viewed from the bottom of the probe 1, from which it is seen that the tip portion is composed of a first curved surface of a radius of curvature r_1 of which contour lines are dense and a second curved surface of a radius of curvature r_2 of which contour lines are spares, these two curved surfaces constitute a continuous spherical surface.

[0024]

In the conventional technique, there was no proposition that proposes suitable configurations and materials for the probe tip by making the mechanism

of the phenomenon clear from the view point of deformation due to the contact between the probe tip and the aluminum pad. Therefore, an intensive study and experiments were conducted on the process for easily generating the shear deformation and for preventing the attachment of aluminum. The shear deformation generates along the slip surface of the metallic crystalline surface. On the other hand, the crystalline direction 3 of the electrode pad 2 at the time of spattering is (111) which is the so-called C-axis orientation. The angle this slip surface 4 of (111) make with respect to the electrode pad is zero degree. Also, the slip surface 5 that has the smallest angle with respect to the electrode pad surface are (110), (101) and (011), of which angle is 35.3 degrees. If the shear generates only at the angles of slip surfaces, then the shears generate only at incremental angles such as 0 degree or 35.3 degrees

[0025]

However, it was determined from the experimental results that the shears generate at an angle intermediate between the slip surfaces 4 and 5 and not at incremental angles. This is believed because shears that occur along the above slip surfaces 4 and 5 are combined and resulted in a shear 11 as shown in Fig. 2. Once a slip is generated in the direction of the slip surface 4 (0 degree), the slip pieces in this direction are subjected to a compression force in the 0 degree and prevented from further slipping from that position. Therefore, the slip in the direction of 35.3 degrees takes place more easily than the slip in the direction of 0 degree, so that the slip that takes place next is the slip in the direction of 35.3 degrees. When the angle θ between the probe tip and the pad surface shown in Fig. 1 is less than 35.3 degrees, the slip pieces are pushed into a narrower space, resulting in that a further slippage is prevented. In this state, the slip in the direction of 0 degree is easier to take place than the slip in the direction of 35.3 degrees, forming the slip in the direction of 0 degree. Therefore, the slips of 0 degree and 35.3 degrees are repeatedly generated and, as a result of this combination, the shears of an angle intermediate between 0 degree and 35.3 degrees are formed.

[0026]

According to an experiment in which the angle of the tangential direction 7 of the probe tip was changed, the angle between the tangential direction 7 of the probe tip and the electrode pad surface at which the above shearing can

take place is from 15 degrees to 35 degrees and a stable shearing takes place at from 17 degrees to 30 degrees. Therefore, when the tip configuration of the probe tip is such that the angle defined between the tangential direction vector 7 of the probe tip and the electrode pad surface is from 15 degrees to 35 degrees and preferably from 17 degrees to 30 degrees, the oxide film 8 on the surface of the electrode pad can be broken and establish a good contact with the fresh electrode pad surface to obtain a sufficient electrical conduction. The relationship between the radius of curvature r of the probe tip and the thickness t of the electrode pad which can provide the above discussed tangential angle can be expressed by $6t \leq r \leq 30t$ and $8t \leq r \leq 23t$. Such the phenomenon can be seen in common in metals of face centered cube lattice such as Al, Au, Cu, Al-Cu alloy, Al-Si and the like.

[0027]

Fig. 3 illustrates the probe trace generated on the aluminum pad 2 through the use of the probe 1. Since the aluminum 31 sheared and purged by the probe tip portion has the laminar structure (lamination), it is determined that the probe tip portion has caused the series of shearing deformations in the test pad material. The above laminar structure is laminated to have a thickness (about $1.5 \mu\text{m}$ in this example) greater than the thickness of the aluminum pad of $0.8 \mu\text{m}$, and the removal configuration is that projections are formed in front of the probe tip portion on the aluminum pad as viewed in the direction of slip of the probe. An example of a removal configuration according to the conventional technique is shown in Fig. 4, from which it is seen that substantially no removal is achieved in the forward direction.

[0028]

It is now clear from the analysis of the contact mechanism and the observation of the removal state that the problems raised when the probe tip is flat or a spherical surface has a large radius of curvature can be explained by the following two phenomena. First, the projection formed slightly due to the removal of the electrode pad material in the forward direction as viewed in the probe slipping direction and the electrical contact is established under or rear of the probe tip portion. However, the slip surface direction and the pressurizing direction are not coincide under or the rear of the probe, so that the fresh surface cannot easily be formed. That is, the oxide film remains between the

needle and the electrode pad. Therefore, by making the contact surface area large, an electrical contact is maintained even when the fresh surface is only a small portion. Secondly, when the fresh surface is formed, another problem of the attachment of aluminum to the probe raises. When this aluminum oxides and could not be removed at the time of next probing, the electrical contact is improper.

[0029]

On the other hand, according to the present invention, the contact angle defined between the electrode pad surface and the probe is set so that the slip is easily generated and the fresh surface is formed at the forward face of the probe to establish an electrically intimate contact surface therethrough (because of the force in the longitudinal direction of the probe is applied). Although aluminum attaches to this surface as in the conventional technique, it is positioned in the direction of the slip of the probe at the next probing, so that it is removed by a massive separating force applied at that time, whereby a contact with the fresh surface is always maintained. Accordingly, in the present invention, the residual aluminum is located at the position close to the side surface of the second curved surface where no electrical contact is necessary. The results of the conduction tests of the probe of the present invention in comparison to the conventional probe are shown in Fig. 5, according to the conventional probe as shown in (b), the improper contacts having the resistance of more than 1 ohm are generated even at the contact of 500th times, it is seen that no failure of electrical conduction is occurred even when the contact of 10000 times were carried out with the test probe of the present invention.

[0030]

Next, advantageous results of this test probe on a semiconductor device will be described. According to the present invention, a trace of slip of the probe on the electrode pad of the semiconductor device is formed and particularly the laminar stack of removed material is formed at the forward end of the trace. While the probe trace is formed with the conventional probe, it is desired to be smaller for the subsequent wire-bonding step. In particular, for the smaller semiconductor devices, the electronic circuitries are highly integrated and the wiring pattern width as well as the electrode pads is getting smaller. However, it was not possible to make the probe trace smaller with the

conventional probe because the reliability of the electrical contact becomes worse. This is because the electrical contact is established at the bottom surface of the probe tip. Therefore, it has been necessary for the probe trace to have a width of the order of $20\ \mu\text{m}$ and a length of the order of $40\ \mu\text{m}$ (see Figs. 3 and 4) and, when the contact is not stable, the probe has been applied for the probing to the same electrode pad, resulting in a still larger probe trace.

[0031]

According to the present invention on the other hand, the probe trace can be made as small as to have a width of $12\ \mu\text{m}$ and a length of $20\ \mu\text{m}$. Also, the observation of the bonded portion of the wire-bonding has revealed that the alloy layer which is the index of the stability of the bonding on the probe trace is not sufficiently formed and that the difference in size of the probe trace significantly affects the quality of the wire bonding. That is, the size of the wire-bonding portion is set to be a circle of a diameter of $65\ \mu\text{m}$ for an electrode pad of $80\ \mu\text{m}$ at one side. For the compact semiconductor device in the future, the one side of the electrode pad should be $65\ \mu\text{m}$ and the bonding area should have a diameter of about $55\ \mu\text{m}$. The area of the probe trace was $800\ \mu\text{m}^2$ for the conventional probe and $240\ \mu\text{m}^2$ for the probe of the present invention, so that the probe trace according to the conventional probe is sufficiently large in comparison with the bonding area of $2400\ \mu\text{m}^2$ for the small electrode pad ($55\ \mu\text{m}$ diameter) to deteriorate the quality of bonding, whereas in the present invention in which the probe trace area is $240\ \mu\text{m}^2$ which is about $1/3$ of that according to the conventional probe, generating no deterioration in bonding. For a small electrode pad and particularly in the long-term reliability, about 5% of the probe traces were improper in poor opening with the conventional probe, whereas in the present invention there were no failure.

[0032]

If the radius of curvature of the probe tip is made small, the pressure applied to the electrode pad becomes high and generates damages (cracks) to the electrode pad. Usually, the probe is pressed against the semiconductor device with a force of the order of 7gf and, in the conventional probe, if the force is decreased to 3gf for example in correspondence with the reduced contact surface area, the poor contact was formed. This is because the conventional probe is designed so that a sufficient electrical conduction can be established

even when the fresh surface is small due to the deviation. With a small contact surface area, the fresh surface area is also small and fluctuated in relation thereto, resulting in the poor contacts. Therefore, it was determined that the arrangement of the probe is effective for the prevention of the damages to the electrode pad in which, as in the present invention, the front of the probe as viewed in the direction of slip of the probe is configured for an easy formation of the fresh surface of the electrode pad (a spherical curved surface of a radius of curvature r_1), while the area of the bottom surface (a spherical curved surface of a radius of curvature r_2) out of the front surface and the bottom surface for supporting the probe pressure is made large. That is, in the present invention, the electrical contact is ensured at the front surface or the first curved surface and the stress is decreased by the bottom surface or the second curved surface. At that time, since the arrangement is such that the probe slightly flex and rotate by the overdrive to make the contact surface area at its maximum at the time of overdrive completion at which the probe pressure is the highest, the pressure applied to the electrode pad can be lowered.

[0033]

Also, by making the tip portion spherical, the contacting surface area is advantageously stable differing from the flat surface heretofore proposed even when the height of the individual probes is different (usually deviation of $10\ \mu\text{m}$ or so is observed). The final load applied to the probe when the probe is pushed by a predetermined amount of over-drive can be set at a desired value by suitably selecting the thickness or length of the probe. However, the load inevitably increases as the over-drive progresses. Since the present invention is arranged such that contact area between the probe tip and the electrode pad increases as the progress of the over-drive, the pressure applied to the semiconductor device does not increase even when the height of the probe has deviation, whereby the damages to the electrode pad can be prevented.

[0034]

It is to be noted that while the tilt angle of the probe 1 is made 8 degrees in the above conduction tests, the angle for the typical probe is of the order of 6 degrees, and a good result can be expected with regard to the contact stability even with this angle. However, it is desirable to make the tilt angle larger in order to prevent the damages since the contact area is limited to

be small in the present invention and, taking the dislocation of the probe from the electrode pad 2 into consideration, the preferable tilt angle is within a range of from 8 degrees to 12 degrees.

[0035]

A manufacturing method and device for easily providing the above-described first curved surface and the second curved surface at the tip portion have been found. The manufacturing method is as described below in conjunction with Fig. 6. In the figure, 12 is an electrolyte liquid. First, the tip portion is formed into a substantially axially symmetrical spherical surface by a general electrolyte abrasion or abrasion using the Si abrasive particles. Then, a first curved surface of a first radius of curvature and a second curved surface of a second radius of curvature smaller than the first radius of curvature are formed by an abrasion device which has an elastically deformable abrasion member secured on a substrate. The abrasion member used may be an elastically deformable thick film of abrasive material, such as a film containing abrasive therein, a film having the abrasive attached on the surface or an elastic deformable thin film attached through a metallic film. More specifically, a silicon substrate 13 is coated or bonded by a polyimide sheet 14 having a thickness of $50\text{ }\mu\text{m}$, a thin Ti film 15 of a thickness of $100\text{ }\text{\AA}$ is formed on it, and then a TiN film of a thickness of $2\text{ }\mu\text{m}$ is formed thereon as an abrasive material. A thick resin layer containing Si abrasive particles having a thickness of $300\text{ }\mu\text{m}$ which is attached to the silicon substrate may also be used.

[0036]

Polishing of the tip portion is carried out by repeatedly moving up and down the probe attached to the probe card and pressed against the abrasive material under pressure with an over-drive amount (several $100\text{ }\mu\text{m}$) greater than the over-drive amount at the time of the wafer test. The tip of the probe attached to the probe card at an angle therewith is forced to make a sliding movement along the abrasive member due to the vertical movement of the probe card. The probe tip portion is embraced by the elastically deformed abrasive to allow the second curved surface having the second radius of curvature r_2 to be formed. The radius of curvature r_2 can be adjusted by the thickness of the abrasive member and the elasticity. When the probe may be first moved along the surface for a predetermined distance after it is brought into

contact with the abrasion device and then moved back and forth about this new position on the abrasion device, the second curved surface can be more selectively polished.

[0037]

The abrasion member may be made by directly securing the abrasive material to a low-rigidity material attached to a high-rigidity substrate or by securing a thick resin film of low rigidity and containing abrasive material to a high-rigidity substrate instead of the above-described material and structure. It should be noted that the probe should be able to move on the abrasion device with the surface of the device slightly elastically depressed or penetrate into the abrasive material during the movement or, preferably, the probe slides along the surface of the elastic abrasive member, whereby the tip portion can easily be provided with a surface having a different radius of curvature.

[0038]

The contact stability is significantly changed according to whether or not the shear deformation of the electrode pad can be easily generated even with the same spherical surface. Fig. 7 illustrates the test results of contact lifetime against various radius of curvature with an electrode pad of $0.8 \mu\text{m}$ thickness of a typical integrated semiconductor device such as a DRAM. It is seen from the graph that good results of the contact life time can be obtained with the radius of curvature of from 7 to $30 \mu\text{m}$, preferably from 10 to $20 \mu\text{m}$. The radius of curvature of equal to or less than $7 \mu\text{m}$ is too small to transmit a sufficient force to the first surface of the electrical conduction surface and the surface area is small, and the upper limit of from 20 to $30 \mu\text{m}$ substantially coincide with the upper limit of $24 \mu\text{m}$ where the shear of the electrode pad generate.

[0039]

While the thickness of the electrode pad changes, the suitable radius of curvature r_1 also changes accordingly and the radius of curvature r_1 should satisfy

$$9t \leq r_1 \leq 35t$$

[0040]

While the probe tip portion of the present invention has been described as being a spherical surface for an easy explanation of the relationship between

the angle of slip in which the shearing deformation of the electrode pad takes place, the tip portion may not be a perfect sphere and a similar results can be obtained with a curved surface configuration close to a sphere.

[0041]

Also, while the Al-Cu alloy has been explained as an example of the test pad material, the similar advantageous results can be obtained when the electrode pad material is aluminum, Al-Si-Cu alloy, copper or the like which exhibits slip deformation (shear deformation) similar to that of aluminum.

[0042]

Embodiment 2

Fig. 8 is diagrammatic illustrations of the results of the scanning electron microscope (SEM) observation of the systems of the test probe according to the second embodiment and a typical probe. Fig. 8(a) shows the system of the typical tungsten probe and Fig. 8(b) is the system of this tungsten probe after the heat treatment. Since the tungsten probe is made of a sintered porous material, the sintered material includes voids. In order to eliminate the voids, the sintered material is rolled by machining and wire-drawn into a wire to provide needle crystalline system. The voids or cavities however still remain by 1 - 2 % and it is therefore desirable to apply the heat treatment for collapsing the cavities includes. However, when the heat treatment at the recrystallization temperature range for the tungsten material is achieved, the needle-like crystal system of the tungsten material is destroyed and the probe becomes brittle to deteriorate the strength of material inherent to tungsten is deteriorated, so that it is not possible to apply such the heat treatment to the thin probe such as that used in the present invention. Thus, a method for collapsing the cavities within the tungsten material was found according to which a high pressure is applied to the probe from outside at a relatively low temperature so that the multiplier effect of temperature and pressure is utilized.

[0043]

The metallic material wire-drawn such as the probe has a pretty high work strain (residual stress) within the material. Due to this work strain, the chemical potential energy of the metal atoms arranged at random particularly around the crystal grain boundary is high. Accordingly, this metallic material high in the work strain is heated to a temperature equal to or less than the

recrystallization temperature and put it under a hydraulic pressure from the outside to collapse the cavities positioned around the crystal grain boundary within the metallic material. The heat treatment condition is at a temperature equal to or less than the recrystallization temperature of the bulk material, the pressure is equal to or more than that needed to generate the slip of the material and the treatment time is until almost all of the movement of the atoms of the metallic material to be treated comes to stop. More particularly, the treatment temperature is 300°C - 600°C, the treatment pressure is 200 - 2000 atms and the treatment time is 0.5 to 5 hours, whereby the cavities can be decreased. It was determined from the experiment that the cavities are significantly reduced particularly when the treatment temperature is 500°C, the treatment pressure is equal to or more than 1000 atmospheric pressure and the treatment time is equal to or more than 1 hour.

[0044]

As for the pressure conditions, the processing time is shorter when the pressure is higher. While the typical cavity collapsing heat treatment is achieved at a temperature equal to or above the recrystallization temperature of the material (usually a temperature 0.4 - 0.5 times higher the melting point of the material) and under a high pressure (referred to as HIP treatment), according to the present invention, the cavities can be collapsed by the heat treatment at a temperature one digit lower as compared to the melting point 3,400°C of the tungsten as shown in Figs. 8(a) and 8(b). Also the brittleness of the material is not increased as in the heat treatment at or above the recrystallization temperature. With a thick probe of a diameter of about 5mm, the above heat treatment with the above heat treatment conditions was achieved and confirmed that the cavity defects were remained. That is, it was determined that the heat treatment of the present invention should be achieved after the wire drawing process to the size of the probe of the order of 150 μ m - 300 μ m.

[0045]

Further, it was found that this heat treatment causes the crystal orientation to be significantly coincided with the direction of wire drawing of the probe and that the etching rate and abrasion rate upon working the probe tip portion becomes uniform due to this effect, allowing the tip of the probe to be a

very smooth flat surface. This causes the probe tip to be difficult to be attached by the oxides, realizing a probe of a good electrical conduction. The surface roughness of the flat surface may preferably be equal to or less than 0.1 μm .

[0046]

Also, since the mechanical properties are even (The Young's modulus after the treatment was 22.3 - 26.3kgf/mm² while the Young's module before treatment was 18.8 - 25.2kgf/mm².) as shown in Table 1, an excessive over-drive and the load can be decreased in view of the deviation of the probe by the probing through the use of the probe card to which the probe is attached.

[0047]

[Table 1]

	tensile load	Young's modulus
sample	gf	x10 ³ kgf/mm ²
before heat treatment	12.800	18.8
	12.960	25.2
	13.060	18.8
after heat treatment	13.520	22.3
	13.800	23.8
	13.840	26.3

[0048]

By using this heat-treated probe material, the probe having the radius of curvature of the tip of 25 μm according to the first embodiment is used, then the number of times at which the continuous probing for the stable electrical contact resistance is possible was improved as compared to the first embodiment to more than 200,000 times, which is more than 10 times larger than the first embodiment, resulting in the significant reduction of the test time and costs.

[0049]

While the description has been made mainly in terms of the probe and the probe card for testing wafer of the semiconductor integrated circuit, according to the contact method of the present invention, a final test of an electrical conduction can be achieved by the concept of the present invention in case of the contact to the lead frame after the semiconductor integrated circuit is packaged, for example. Also, the probe can be applied to the operational test of an electronic circuit board to which a semiconductor integrated circuit or display device or the like is mounted.

[0050]

[Advantageous Results]

As has been described, according to the semiconductor device test probe of the first construction of the present invention, the probe includes a side surface portion and a tip portion, the tip portion is a spherical curved surface, and that the radius of curvature r of the curved surface, with respect to the electrode pad thickness t , is made $9t \leq r \leq 35t$, so that the probe tip can efficiently shear and deform the electrode pad during the probing to establish a sufficient electrical conduction between the probe tip and the electrode pad, enabling a reliable electrical property test of the semiconductor device.

[0051]

According to the semiconductor device test probe of the second construction of the present invention, the probe includes a side surface portion and a tip portion, the tip portion is a spherical curved surface, the curved surface has a first curved surface which is substantially positioned in the direction of slippage of the probe when the probe is urged against the electrode pad and slipped relative to the electrode pad and which is larger than a second curved surface opposite to the first curved surface, and that the radius of curvature of the first curved surface is made of from $7\mu\text{m}$ to $30\mu\text{m}$, so that the probe tip can efficiently shear and deform the electrode pad during the probing to form a small contacting surface that establishes a sufficient electrical conduction between the probe tip and the electrode pad without the need for the cleaning of the probe tip, enabling that the semiconductor device be not damaged and no poor bonding is generated.

[0052]

According to the method for manufacturing the semiconductor device test probe of the third construction of the present invention, in the test probe as in the second construction, the method comprises the steps of: roughing the tip portion of the curved surface by abrading by means of electrolyte abrasion or abrading particles to form a symmetrical spherical curved surface; and finishing the tip portion by sliding it on an abrasive member comprising an elastically deformable thick film fixed to a substrate and having abrasive particles therein or thereon directly or through a metallic film, so that it is possible to easily manufacture the probe that can efficiently shear and deform the electrode pad

during the probing to form a small contacting surface that establishes a sufficient electrical conduction between the probe tip and the electrode pad without the need for the cleaning of the probe tip, enabling that the semiconductor device be not damaged and no poor bonding is generated.

[0053]

According to the semiconductor device test probe of the fourth construction of the present invention, in the first or second construction, the probe is made of a sintered metallic material made from a powdery material, and the probe is heat treated, the heat treatment conditions being a non-oxidizing atmosphere, at the treatment temperature of equal to or less than the recrystallization temperature of the metallic material and the non-oxidizing gas is pressurized, so that it is possible to provide a test probe in which the cavity defects in the probe are decreased and the mechanical property is uniform, the attachment of the oxide to the probe tip can be prevented and therefore the stable electrical conduction can be continuously maintained.

[0054]

According to the semiconductor device of the fifth construction of the present invention, the test is achieved by urging the semiconductor device test probe as in one of the first, second and fourth constructions against the electrode pad of the semiconductor device, providing a relative sliding movement between the probe and the electrode pad to expel the electrode pad material by making a lamination stack to provide a small probe trace, so that the generation of the poor wire-bonding can be prevented.

[BRIEF DESCRIPTION OF THE DRAWINGS]

[Fig. 1] An explanatory view showing the state of the probe and the electrode pad of the first embodiment of the present invention:

[Fig. 2] An explanatory view showing the state of the probe and the electrode pad of the first embodiment of the present invention:

[Fig. 3] An explanatory view showing the probe trace on the aluminum electrode pad formed by the probe of the first embodiment of the present invention as compared to the case where a general probe was used:

[Fig. 4] An explanatory view showing the probe trace on the aluminum electrode pad formed by the probe of the first embodiment of the present invention as compare to the case where a general probe was used:

[Fig. 5] Explanatory views showing the contact stability when the probe of the first embodiment of the present invention was used in comparison with that of a typical example:

[Fig. 6] Explanatory views showing the state of the probe and the abrasion device:

[Fig. 7] An explanatory view showing the relationship between the tip shape of the probe and the contact stability when the probe of the first embodiment of the present invention was used:

[Fig. 8] Diagrammatic illustrations of the results of the SEM observation of the probe according to the second embodiment of the present invention:

[Fig. 9] Explanatory view of the conventional probe device as well as the state of the electrode pad and the probe:

[Fig. 10] An explanatory view illustrating another conventional probe: and

[Fig. 11] An explanatory view illustrating still another conventional prove.

[Explanation of Reference Numerals]

1 probe needle, 2 electrode pads, 3 crystalization orientation of the electrode pad, 4 sliding surface at (111), 5 sliding surfaces at (110)(101)(011), 6 the smallest sliding surface, 7 tangential vector of the probe tip, 8 oxide film on the electrode pad surface, 9 an electrically conducting portion, 10 an oxide film attached to the probe, 11 sheared pieces, 12 electrolyte liquid, 13 substrate, 14 resin, 16 abrasive material, 31 aluminum expelled by the probe tip, 200 probe needle tip, 201 probe card, 202 probe needle, 203 electrode pad, 204 electrode pad surface oxidized film, 205 probe needle "heel" portion, 206 electrically conductive portion.

[DOCUMENT NAME] ABSTRACT

[Abstract]

[Problem] The provision of a test probe, its manufacturing method and a semiconductor device tested by the test probe of high productivity of which true contact surface between the probe tip and the electrode pads is made large to provide a reliable good electrical contact with a small amount of probe slippage.

[Measure for Solving] In a wafer testing probe for being urged against an electrode pad of an integrated semiconductor device to establish an electrical contact against the electrode pad for testing functions of the semiconductor device. The probe has a side surface portion and a tip portion, the tip portion is a spherical curved surface, and the curved surface has a radius of curvature r expressed by $9t \leq r \leq 35t$, where r is the radius of curvature of the spherical surface and t is the thickness of the electrode pad.

[Selected Figure] Fig. 1